

## ETC5064/64-X ETC5067/67-X

# SERIAL INTERFACE CODEC/FILTER WITH RECEIVE POWER AMPLIFIER

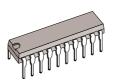
- COMPLETE CODEC AND FILTERING SYSTEM INCLUDING:
  - Transmit high-pass and low-pass filtering.
  - Receive low-pass filter with sin x/x correction.
  - Active RC noise filter.
  - μ-law or A-law compatible CODER and DE-CODER.
  - Internal precision voltage reference.
  - Serial I/O interface.
  - Internal auto-zero circuitry.
  - Receive push-pull power amplifiers.
- µ-LAW ETC5064
- A-LAW ETC5067
- MEETS OR EXCEEDS ALL D3/D4 AND CCITT SPECIFICATIONS.
- ±5 V OPERATION.
- LOW OPERATING POWER-TYPICALLY 70 mW
- POWER-DOWN STANDBY MODE-TYPICALLY 3 mW
- AUTOMATIC POWER DOWN
- TTL OR CMOS COMPATIBLE DIGITAL INTER-FACES
- MAXIMIZES LINE INTERFACE CARD CIR-CUIT DENSITY
- 0°C TO 70°C OPERATION: ETC5064/67
- -40°C TO 85°C OPERATION: ETC5064-X/67-X

#### **DESCRIPTION**

The ETC5064 ( $\mu$ -law), ETC5067 (A-law) are monolithic PCM CODEC/FILTERS utilizing the A/D and D/A conversion architecture shown in the Block Diagrams and a serial PCM interface. The devices are fabricated using double-poly CMOS process.

Similar to the ETC505X family, these devices feature an additional Receive Power Amplifier to provide push-pull balanced output drive capability. The receive gain can be adjusted by means of two external resistors for an output level of up to  $\pm~6.6~\rm V$  across a balanced  $600\Omega$  load.

Also included is an Analog Loopback switch and  $\overline{TS}_X$  output.



DIP20 (Plastic) N

#### **ORDERING NUMBERS:**

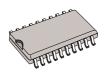
ETC5064N ETC5064N-X ETC5067N ETC5067N-X



PLCC20

#### **ORDERING NUMBERS:**

ETC5064FN ETC5064FN-X ETC5067FN ETC5067FN-X



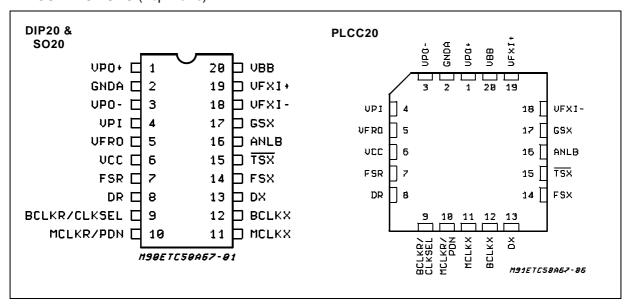
**SO20** D

#### **ORDERING NUMBERS:**

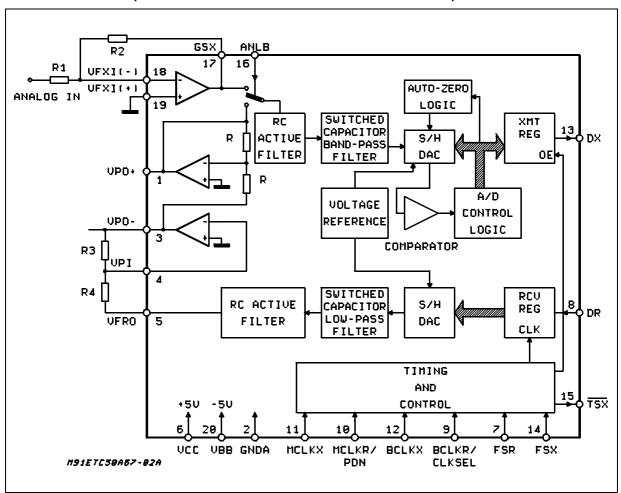
ETC5064D ETC5064D-X ETC5067D ETC5067D-X

November 1994 1/18

#### PIN CONNECTIONS (Top views)



## **BLOCK DIAGRAM (ETC5064 - ETC5064-X - ETC5067 - ETC5067-X)**



## **PIN DESCRIPTION**

Name	Pin Type (*)	N	Description
VPO <sup>+</sup>	0	1	The Non-inverting Output of the Receive Power Amplifier
GNDA	GND	2	Analog Ground. All signals are referenced to this pin.
VPO <sup>-</sup>	0	3	The Inverting Output of the Receive Power Amplifier
VPI	I	4	Inverting Input to the Receive Power Amplifier. Also powers down both amplifiers when connected to $V_{\text{BB}}$ .
VF <sub>R</sub> O	0	5	Analog Output of the Receive Filter.
V <sub>CC</sub>	S	6	Positive Power Supply Pin. $V_{CC}$ = +5V ±5%
FS <sub>R</sub>	1	7	Receive Frame Sync Pulse which enable BCLK <sub>R</sub> to shift PCM data into $D_R$ . FS <sub>R</sub> is an 8KHz pulse train. See figures 1 and 2 for timing details.
$D_R$	I	8	Receive Data Input. PCM data is shifted into $D_R$ following the FS $_R$ leading edge
BCLK <sub>R</sub> /CLKSEL		9	The bit Clock which shifts data into $D_R$ after the $FS_R$ leading edge. May vary from 64KHz to 2.048MHz. Alternatively, may be a logic input which selects either 1.536MHz/1.544MHz or 2.048MHz for master clock in synchronous mode and BCLK $_X$ is used for both transmit and receive directions (see table 1). This input has an internal pull-up.
MCKL <sub>R</sub> /PDN	_	10	Receive Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with $MCLK_X$ , but should be synchronous with $MCLK_X$ for best performance. When $MCLK_R$ is connected continuously low, $MCLK_X$ is selected for all internal timing. When $MCLK_R$ is connected continuously high, the device is powered down.
MCLK <sub>X</sub>	I	11	Transmit Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with $MCLK_R$ .
BCLK <sub>X</sub>	I	12	The bit clock which shifts out the PCM data on D <sub>X</sub> . May vary from 64KHz to 2.048MHz, but must be synchronous with MCLK <sub>X</sub> .
$D_X$	0	13	The TRI-STATE®PCM data output which is enabled by FS <sub>X</sub> .
FS <sub>X</sub>	I	14	Transmit frame sync pulse input which enables $BCLK_X$ to shift out the PCM data on $D_X$ . $FS_X$ is an 8KHz pulse train. See figures 1 and 2 for timing details.
TS <sub>X</sub>	0	15	Open drain output which pulses low during the encoder time slot. Must to be grounded if not used.
ANLB	I	16	Analog Loopback Control Input. Must be set to logic '0' for normal operation. When pulled to logic '1', the transmit filter input is disconnected from the output of the transmit preamplifier and connected to the VPO <sup>+</sup> output of the receive power amplifier.
GS <sub>X</sub>	0	17	Analog output of the transmit input amplifier. Used to set gain externally.
VF <sub>X</sub> I <sup>-</sup>	I	18	Inverting input of the transmit input amplifier.
$VF_XI^+$	I	19	Non-inverting input of the transmit input amplifier.
$V_{BB}$	S	20	Negative Power Supply Pin. V <sub>BB</sub> = -5V ±5%

(\*) I: Input, O: Output, S: Power Supply.  $\mbox{TRI-STATE} \circledast$  is a trademark of National Semiconductor Corp.

#### **FUNCTIONAL DESCRIPTION**

#### **POWER-UP**

When power is first applied, power-on reset circuitry initializes the device and places it into the power-down mode. All non-essential circuits are deactivated and the  $D_X$  and  $VF_RO$  outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the MCLKR/PDN pin and FSx and/or FSR pulses must be present. Thus 2 power-down control modes are available. The first is to pull the MCLKR/PDN pin high; the alternative is to hold both FSx and FSR inputs continuously low. The device will power-down approximately 2 ms after the last FSx pulse. The TRI-STATE PCM data output, Dx, will remain in the high impedance state until the second FSx pulse.

#### SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to MCLK<sub>X</sub> and the MCLK<sub>R</sub>/PDN pin can be used as a power-down control. A low level on MCLK<sub>R</sub>/PDN powers up the device and a high level powers down the device. In either case, MCLKX will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to BCLK<sub>X</sub> and the BCL<sub>R</sub>/CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193 rd clock pulse each frame.

With a fixed level on the BCLK<sub>R</sub>/CKSEL pin, BCLK<sub>X</sub> will be selected as the bit clock for both the transmit and receive directions. Table 1 indicates the frequencies of operation which can be selected, depending on the state of BCLK<sub>R</sub>/CLKSEL. In this synchronous mode, the bit clock, BCLK<sub>X</sub>, may be from  $64 \, \text{kHz}$  to  $2.048 \, \text{MHz}$ , but must be synchronous with MCLK<sub>X</sub>.

**Table 1:** Selection of Master Clock Frequencies.

BCLKR/CLKSEL	Master Clock Frequency Selected				
BOLKNOLKSEL	ETC5067 ETC5067-X	ETC5064 ETC5064-X			
Clocked	2.048MHz	1.536MHz or 1.544MHz			
0	1.536MHz or 1.544MHz	2.048MHz			
1 (or open circuit)	2.048MHz	1.536MHz or 1.544MHz			

Each FS $_X$  pulse begins the encoding cycle and the PCM data from the previous encode cycle is shift out of the enabled D $_X$  output on the positive edge of BCLK $_X$ . After 8 bit clock periods, the TRISTATE D $_X$  output is returned to a high impedance state. With an FS $_R$  pulse, PCM data is latched via the D $_R$  input on the negative edge of BCLK $_X$  (or on BCKL $_R$  if running). FS $_X$  and FS $_R$  must be synchronous with MCLKX/ $_R$ .

#### **ASYNCHRONOUS OPERATION**

For asynchronous operation, separate transmit and receive clocks may be applied. MCLKX and MCLKR must be 2.048 MHz for the ETC5067 or 1.536 MHz, 1.544 MHz for the ETC5064, and need not be synchronous. For best transmission performance, however, MCLK<sub>R</sub> should be synchronous with MCLK<sub>X</sub>, which is easily achieved by applying only static logic levels to the MCLK<sub>R</sub>/PDN pin. This will automatically connect MCLK<sub>X</sub> to all internal MCLK<sub>R</sub> functions (see pin description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FS<sub>X</sub> starts each encoding cycle and must be synchronous with MCLK<sub>X</sub> and BCLK<sub>X</sub>. FS<sub>R</sub> starts each decoding cycle and must be synchronous with BCLK<sub>R</sub>. BCLK<sub>R</sub> must be a clock, the logic levels shown in Table 1 are not valid in asynchronous mode. BCLK<sub>X</sub> and BCLK<sub>R</sub> may operate from 64kHz to 2.048 MHz.

#### SHORT FRAME SYNC OPERATION

The device can utilize either a short frame sync pulse or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses. FSx and FSR, must be one bit clock period long, with timing relationships specified in figure 2. With FS<sub>X</sub> high during a falling edge of BCLKR, the next rising edge of BCLK<sub>X</sub> enables the D<sub>X</sub> TRI-STATE output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the Dx output. With FS<sub>R</sub> high during a falling edge of BCLK<sub>R</sub> (BCLK<sub>X</sub> in synchronous mode), the next falling edge of BCLKR latches in the sign bit. The following seven falling edges latch in the seven remaining bits. Both devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

#### LONG FRAME SYNC OPERATION

To use the long frame mode, both the frame sync pulses,  $FS_X$  and  $FS_R$ , must be three or more bit clock periods long, with timing relationships specified in figure 3. Based on the transmit frame sync  $FS_X$ , the device will sense whether short or long frame sync



pulses are being used. For 64 kHz operation, the frame sync pulses must be kept low for a minimum of 160 ns (see Fig 1). The D $_{\rm X}$  TRI-STATE output buffer is enabled with the rising edge of FS $_{\rm X}$  or the rising edge of BCLK $_{\rm X}$ , whichever comes later, and the first bit clocked out is the sign bit. The following seven BCLK $_{\rm X}$  rising edges clock out the remaining seven bits. The D $_{\rm X}$  output is disabled by the falling BCLK $_{\rm X}$  edge following the eighth rising edge, or by FS $_{\rm X}$  going low, whichever comes later. A rising edge on the receive frame sync pulse, FS $_{\rm R}$ , will cause the PCM data at D $_{\rm R}$  to be latched in on the next eight falling edges of BCLK $_{\rm R}$  (BCLK $_{\rm X}$  in synchronous mode). Both devices may utilize the long frame sync pulse in synchronous or asynchronous mode.

#### TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter directly drives the encoder sampleand-hold circuit. The A/D is of companding type according to A-law (ETC5067 and ETC5067-X) or μlaw (ETC5064 and ETC5064-X) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input over load (t<sub>MAX</sub>) of nominally 2.5V peak (see table of Transmission Characteristics). The FS<sub>X</sub> frame sync pulse controls the sampling of the filer output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through  $D_X$  at the next  $FS_X$  pulse. the total encoding delay will be approximately 165 µs (due to the transmit filter) plus 125µs (due to encoding delay), which totals 290µs. Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

#### RECEIVE SECTION

The receive section consist of an expanding DAC which drives a fifth order switched-capacitor low pass filter clocked at 256kHz. The decoder is A-law (ETC5067 and ETC5067-X) or μ-law (ETC5064 and ETC5064-X) and the 5 th order low pass filter corrects for the sin x/x attenuation due to the 8kHz sample and hold. The filter is then followed by a 2 nd order RC active post-filter and power amplifier capable of driving a  $600\Omega$  load to a level of 7.2dBm. The receive section is unity-gain. Upon the occurence of FS<sub>R</sub>, the data at the D<sub>R</sub> input is clocked in on the falling edge of the next eight BCLKR (BCKL<sub>X</sub>) periods. At the end of the decoder time slot, the decoding cycle begins, and 10us later the decoder DAC output is updated. The total decoder delay is about 10 µs (decoder up-date) plus 110 µs (filter delay) plus 62.5µs (1/2 frame), which gives approximately 180µs.

#### RECEIVE POWER AMPLIFIERS

Two inverting mode power amplifiers are provided for directly driving a matched line interface transformer. The gain of the first power amplifier can be adjusted to boost the  $\pm$  2.5V peak output signal from the receive filter up  $\pm$  3.3V peak into an unbalanced  $300\Omega$  load, or  $\pm 4.0V$  into an unbalanced  $15k\Omega$  load. The second power amplifier is internally connected in unity-gain inverting mode to give 6dB of signal gain for balanced loads. Maximum power transfer to a  $600\Omega$  subscriber line termination is obtained by differientially driving a balanced transformer with a  $\sqrt{2}$ : 1 turns ratio, as shown in figure 4. A total peak power of 15.6dBm can be delivered to the load plus termination. Both power amplifier can be powered down independently from the PDN input by connecting the VPI input to VBB saving approximately 12 mW of power.

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
$V_{CC}$	V <sub>CC</sub> to GNDA	7	<b>V</b>
$V_{BB}$	V <sub>BB</sub> to GNDA	-7	V
$V_{\text{IN}}, V_{\text{OUT}}$	Voltage at any Analog Input or Output	$V_{CC}$ +0.3 to $V_{BB}$ -0.3	V
	Voltage at any Digital Input or Output	V <sub>CC</sub> +0.3 to GNDA -0.3	V
$T_{oper}$	Operating Temperature Range: ETC5064/67 ETC5064-X/67-X	-25 to +125 -40 to +125	ပို ပိ
$T_{stg}$	Storage Temperature Range	-65 to +150	ç
	Lead Temperature (soldering, 10 seconds)	300	°C



## **ELECTRICAL OPERATING CHARACTERISTICS**

 $V_{CC}$  = 5.0V ±5%,  $V_{BB}$  = -5V ±5%, GNDA = 0V,  $T_A$  = 0°C to 70°C (ETC5064-X/67-X:  $T_A$  = -40°C to 85°), unless otherwise noted; typical characteristics specified at  $V_{CC}$  = 5.0V,  $V_{BB}$  =-5.0V,  $T_A$  = 25°C; all signals are referenced to GNDA.

DIGITAL INTERFACE (All devices)

Symbol	Parameter		Min.	Тур.	Max.	Unit
$V_{IL}$	Input Low Voltage				0.6	V
$V_{IH}$	Input High Voltage		2.2			V
V <sub>OL</sub>	Output Low Voltage $I_L = 3.2 \text{ mA}$ $I_L = 3.2 \text{ mA}$ , Open Drain	D <sub>X</sub> TS <sub>X</sub>			0.4 0.4	> >
Voн	Output High Voltage IH = 3.2 mA	D <sub>X</sub>	2.4			V
I <sub>IL</sub>	Input Low Current (GNDA $\leq V_{IN} \leq V_{IL}$ )all digital inputs Except BCLK <sub>R</sub>		- 10		10	μΑ
I <sub>IH</sub>	Input High Current ( $V_{IH} \le V_{IN} \le V_{CC}$ ) Except ANLB		- 10		10	μΑ
loz	Output Current in High Impedance State (TRI-STATE) (GNDA $\leq$ V <sub>O</sub> $\leq$ V <sub>CC</sub> )	D <sub>X</sub>	- 10		10	μΑ

## ANALOG INTERFACE WITH TRANSMIT INPUT AMPLIFIER (all devices)

Symbol	Parameter		Min.	Тур.	Max.	Unit
IıXA	Input Leakage Current $(-2.5 \text{ V} \leq \text{V} \leq + 2.5 \text{ V})$	VFxI <sup>+</sup> or VFxI <sup>-</sup>	- 200		200	nA
R <sub>I</sub> XA	Input Resistance $(-2.5 \text{ V} \le \text{V} \le + 2.5 \text{ V})$	$VF_XI^+$ or $VF_XI^-$	10			МΩ
R <sub>O</sub> XA	Output Resistance (closed loop, unity gain)			1	3	Ω
$R_LXA$	Load Resistance	GS <sub>X</sub>	10			kΩ
C <sub>L</sub> XA	Load Capacitance	GS <sub>X</sub>			50	pF
V <sub>O</sub> XA	Output Dynamic Range ( $R_L \ge 10 \text{ k}\Omega$ )	$GS_X$	- 2.8		+2.8	V
$A_VXA$	Voltage Gain (VF <sub>X</sub> I <sup>+</sup> to GS <sub>X</sub> )		5000			V/V
F <sub>U</sub> XA	Unity Gain Bandwidth		1	2		MHz
$V_{OS}XA$	Offset Voltage		- 20		20	mV
$V_{CM}XA$	Common-mode Voltage		- 2.5		2.5	V
CMRRXA	Common-mode Rejection Ratio		60			dB
PSRRXA	Power Supply Rejection Ratio		60			dB

## ANALOG INTERFACE WITH RECEIVE FILTER (all devices)

Symbol	Parameter	Min.	Тур.	Max.	Unit
RoRF	Output Resistance VF <sub>R</sub> O		1	3	Ω
$R_LRF$	Load Resistance (VF <sub>R</sub> O = $\pm$ 2.5 V)	10			kΩ
C <sub>L</sub> RF	Load Capacitance			25	pF
VOS <sub>R</sub> O	Output DC Offset Voltage	- 200		200	mV



## **ELECTRICAL OPERATING CHARACTERISTICS (Continued)**

ANALOG INTERFACE WITH POWER AMPLIFIERS (all devices)

Symbol	Parameter	Min.	Тур.	Max.	Unit
IPI	Input Leakage Current (- 1.0 V ≤ VPI ≤ 1.0 V)	- 100		100	nA
RIPI	Input Resistance (– 1.0 ≤ VPI ≤ 1.0 V)	10			МΩ
VIOS	Input Offset Voltage	- 25		25	mV
ROP	Output Resistance (inverting unity-gain at VPO + or VPO -)		1		Ω
Fc	Unity-gain Bandwidth, Open Loop (VPO )		400		kHz
C <sub>L</sub> P	Load Capacitance (VPO $^+$ or VPO $^-$ to GNDA) $R_L \geq 1500~\Omega$ $R_L = 600~\Omega$ $R_L = 300~\Omega$			100 500 1000	pF
GAp <sup>+</sup>	Gain VPO <sup>-</sup> to VPO <sup>+</sup> to GNDA, Level at VPO <sup>-</sup> = 1. 77 Vrms (+ 3 dBmO)		- 1		V/V
PSRRp	Power Supply Rejection of V <sub>CC</sub> or V <sub>BB</sub> (VPO <sup>-</sup> connected to VPI) 0 kHz - 4 kHz 0 kHz - 50 kHz	60 36			dB

## POWER DISSIPATION (all devices)

Symbol	Parameter	Min.	Тур.	Max.	Unit
I <sub>CC</sub> 0	Power-down Current at ETC6064/67 ETC5064-X/67-X		0.5 0.5	1.5	mA mA
I <sub>BB</sub> 0	Power-down Current at ETC6064/67 ETC5064-X/67-X		0.05 0.05	0.3 0.4	mA mA
I <sub>CC</sub> 1	Active Current at ETC6064/67 ETC5064-X/67-X		7.0 7.0	10.0 12.0	mA mA
I <sub>BB</sub> 1	Active Current at ETC6064/67 ETC5064-X/67-X		7.0 7.0	10.0 12.0	mA mA

## **AII TIMING SPECIFICATIONS**

Symbol	Parameter	Min.	Тур.	Max.	Unit
1/t <sub>PM</sub>	Frequency of master clocks  MCLK <sub>X</sub> and MCLK <sub>R</sub> Depends on the device used and the  BCLK <sub>R</sub> /CLKSEL Pin		1.536 2.048 1.544		MHz
$t_{WMH}$	Width of Master Clock High MCLK <sub>X</sub> and MCLK <sub>R</sub>	160			ns
twmL	Width of Master Clock Low MCLKx and MCLKR	160			ns
t <sub>RM</sub>	Rise Time of Master Clock MCLK <sub>X</sub> and MCLK <sub>R</sub>			50	ns
t <sub>FM</sub>	Fall Time of Master Clock MCLK <sub>X</sub> and MCLK <sub>R</sub>			50	ns
t <sub>PB</sub>	Period of Bit Clock	485	488	15.725	ns
t <sub>WBH</sub>	Width of Bit Clock High (V <sub>IH</sub> = 2.2 V)	160			ns
t <sub>WBL</sub>	Width of Bit Clock Low (V <sub>IL</sub> = 0.6 V)	160			ns
t <sub>RB</sub>	Rise Time of Bit Clock (t <sub>PB</sub> = 488 ns)			50	ns
t <sub>FB</sub>	Fall Time of Bit Clock (t <sub>PB</sub> = 488 ns)			50	ns
tsbfm	Set-up time from $BCLK_X$ high to $MCLK_X$ falling edge. (first bit clock after the leading edge of $FS_X$ )	100			ns
t <sub>HBF</sub>	Holding Time from Bit Clock Low to the Frame Sync (long frame only)	0			ns
t <sub>SFB</sub>	Set-up Time from Frame Sync to Bit Clock (long frame only)	80			ns
t <sub>HBFI</sub>	Hold Time from 3rd Period of Bit Clock FS <sub>X</sub> or FS <sub>R</sub> Low to Frame Sync (long frame only)	100			ns
t <sub>DZF</sub>	Delay Time to valid data from $FS_X$ or $BCLK_X$ , whichever comes later and delay time from $FSX$ to data output disabled $(C_L = 0 \text{ pF to } 150 \text{ pF})$	20		165	ns
t <sub>DBD</sub>	Delay Time from BCLK <sub>X</sub> high to data valid (load = 150 pF plus 2 LSTTL loads)	0		150	ns
t <sub>DZC</sub>	Delay Time from BCLK <sub>X</sub> low to data output disabled	50		165	ns
t <sub>SDB</sub>	Set-up Time from D <sub>R</sub> valid to BCLK <sub>R/X</sub> low	50			ns
t <sub>HBD</sub>	Hold Time from BCLK <sub>R/X</sub> low to D <sub>R</sub> invalid	50			ns
tHOLD	Holding Time from Bit Clock High to Frame Sync (short frame only)	0			ns
tsf	Set-up Time from FS <sub>X/R</sub> to BCLK <sub>X/R</sub> Low (short frame sync pulse) - Note 1	80			ns
t <sub>HF</sub>	Hold Time from $BCLK_{X/R}$ Low to $FS_{X/R}$ Low (short frame sync pulse) - Note 1	100			ns
t <sub>XDP</sub>	Delay Time to TS <sub>X</sub> low (load = 150 pF plus 2 LSTTI loads)			140	ns
twFL	Minimum Width of the Frame Sync Pulse (low level) (64 bit/s operating mode)	160			ns

 $\textbf{Note} : 1. For short frame sync timing. \ FS_X \ and \ FS_R \ must go \ high \ while their respective bit clocks are \ high.$ 

Figure 1:64 k bits/s TIMING DIAGRAM. (see next page for complete timing)

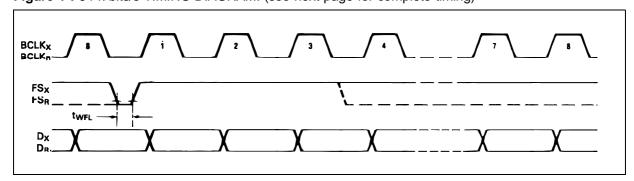


Figure 2 : Short Frame Sync Timing.

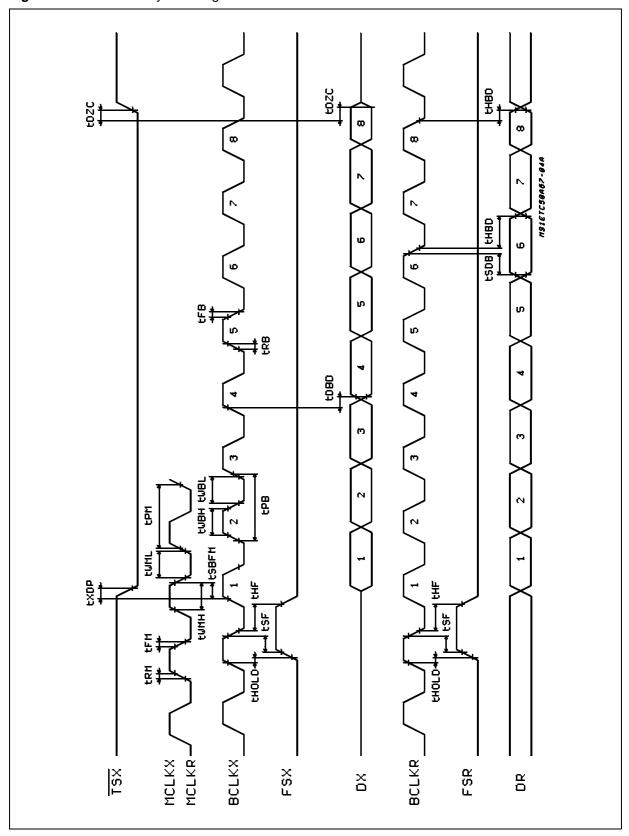
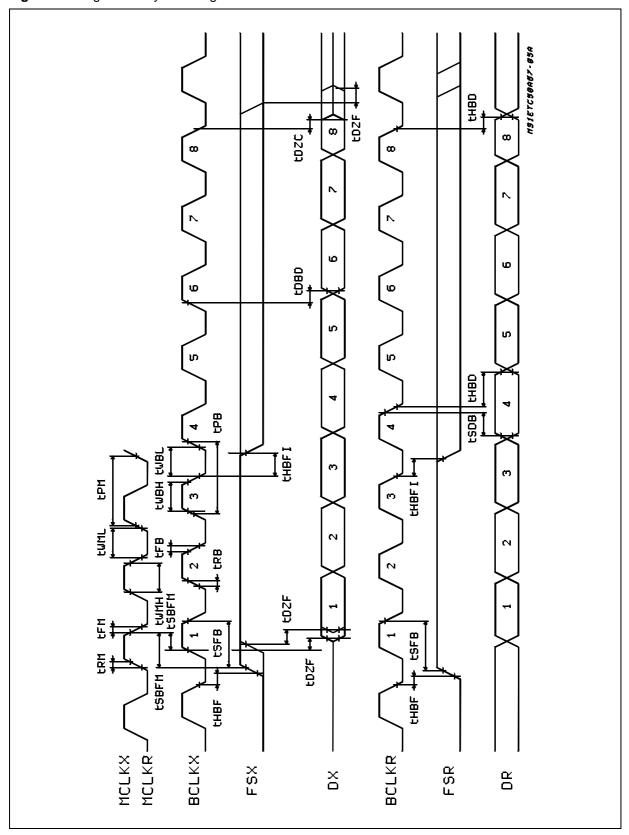


Figure 3: Long Frame Sync Timing.



## TRANSMISSION CHARACTERISTICS

(all devices)  $T_A = 0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$  (ETC5064-X/67-X:  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}$ ),  $V_{CC} = 5\text{V} \pm 5\%$ ,  $V_{BB} = -5\text{V} \pm 5\%$ , GNDA = 0V, f = 1.02kHz,  $V_{IN} = 0\text{dBm0}$  transmit input amplifier connected for unity–gain non–inverting. (unless otherwise specified).

## AMPLITUDE RESPONSE

Symbol	Parameter	Min.	Тур.	Max.	Unit
	Absolute Levels - Nominal 0 dBm0 is 4 dBm (600 $\Omega$ ). 0 dBm0		1.2276		Vrms
t <sub>MAX</sub>		C5067 C5064	2.492 2.501		VPK
G <sub>XA</sub>	Transmit Gain, Absolute ( $T_A = 25^{\circ}C$ , $V_{CC} = 5V$ , $V_{BB} = -5^{\circ}$ Input at $GS_X = 0$ dBm0 at 1020Hz	V) -0.15		0.15	dB
GXR	Transmit Gain, Relative to GXA  f = 16Hz f = 50Hz f = 60Hz f = 180Hz f = 200Hz f = 300Hz -3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4400Hz f = 4600Hz and up, measure response from oHz to 4000	- -2.8 -1.8 -0.15 -0.35 -0.35 -0.7		-40 -30 -26 -0.2 -0.1 0.15 0.20 0.05 0 -14 -32	dB
G <sub>XAT</sub>	Absolute Transmit Gain Variation with Temperature $T_A = 0$ °C to +70°C $T_A = -40$ °C to +85°C (ETC5064-X/67-X)	-0.1 -0.15		0.1 0.15	dB
$G_XAV$	Absolute Transmit Gain Variation with Supply Voltage ( $V_{CC} = 5V \pm 5\%$ , $V_{BB} = -5V \pm 5\%$ )	-0.05		0.05	dB
G <sub>XRL</sub>	Transmit Gain Variation with Level Sinusolidal Test Method Reference Level = -10dBm0 $VF_XI^+$ = -40dBm0 to +3dBm0 $VF_XI^+$ = -50dBm0 to -40dBm0 $VF_XI^+$ = -55dBm0 to -50dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB
GRA	Receive Gain, Absolute (T <sub>A</sub> = 25°C, V <sub>CC</sub> = 5V, V <sub>BB</sub> = -5\ Input = Digital Code Sequence for 0dBm0 Signal at 1020			0.15	dB
G <sub>RR</sub>	Receive Gain, Relative to $G_{RA}$ f = 0Hz to 3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4000Hz	-0.15 -0.35 -0.35 -0.7		0.15 0.20 0.05 0 -14	dB
G <sub>RAT</sub>	Absolute Receive Gain Variation with Temeperature $T_A = 0$ °C to +70°C $T_A = -40$ °C to +85°C (ETC5064-X/67-X)	-0.1 -0.15		0.1 0.15	dB
Grav	Absolute Receive Gain Variation with Supply Voltage ( $V_{CC} = 5V \pm 5\%$ , $V_{BB} = -5V \pm 5\%$ )	-0.05		0.05	dB
G <sub>RRL</sub>	Receive Gain Variation with Level Sinusoidal Test Method; Reference Input PCM code corresponds to an ideally encoded -10dBm0 signal PCM level = -40dBm0 to +3dBm0 PCM level = -50dBm0 to -40dBm0 PCM level = -55dBm0 to -50dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB
$V_{RO}$	Receive Filter Output at $VF_ROR_L = 10K\Omega$	-2.5		2.5	V

## TRANSMISSION CHARACTERISTICS (continued). ENVELOPE DELAY DISTORTION WITH FREQUENCY

Symbol	Parameter	Min.	Тур.	Max.	Unit
DxA	Transmit Delay, Absolute (f = 1600 Hz)		290	315	μs
D <sub>XR</sub>	Transmit Delay, Relative to $D_{XA}$ f = 500 Hz-600 Hz f = 600 Hz-800 Hz f = 800 Hz-1000 Hz f = 1000 Hz-1600 Hz f = 1600 Hz-2600Hz f = 2600 Hz-2800 Hz f = 2800 Hz-3000 Hz		195 120 50 20 55 80 130	220 145 75 40 75 105 155	μs
$D_RA$	Receive Delay, Absolute (f = 1600 Hz)		180	200	μs
D <sub>RR</sub>	Receive Delay, Relative to D <sub>RA</sub> f = 500 Hz-1000 Hz f = 1000 Hz-1600 Hz f = 1600 Hz-2600 Hz f = 2600 Hz-2800 Hz f = 2800 Hz-3000 Hz	- 40 - 30	- 25 - 20 70 100 145	90 125 175	μs

## NOISE

Symbol	Parameter	Min.	Тур.	Max.	Unit
N <sub>XP</sub>	Transmit Noise, P Message (A-LAW, VF <sub>X</sub> I + = 0 V) Weighted 1) ETC5064 ETC5064-X		- 74 - 74	- 69 - 67	dBm0p dBm0p
$N_{RP}$	Receive Noise, P Message Weighted (A-LAW, PCM Code Equals Positive Zero)		- 82	- 79	dBm0p
N <sub>XC</sub>	Transmit Noise, C Message Weighted (μ-LAW, VFxI + = 0 V) ETC5064 ETC5064-X		12 12	15 16	dBrnC0 dBrnC0
N <sub>RC</sub>	Receive Noise, C Message Weighted (μ-LAW, PCM Code Equals Alternating Positive and Negative Zero)		8	11	dBrnC0
$N_{RS}$	Noise, Single Frequency $f = 0 \text{ kHz}$ to 100 kHz, Loop around Measurement, $VF_XI^+ = 0 \text{ V}$			- 53	dBm0
PPSR <sub>X</sub>	Positive Power Supply Rejection, Transmit (note 2) $V_{CC} = 5.0 V_{DC} + 100 \text{ mVrms}, f = 0 \text{ kHz}-50 \text{ kHz}$	40			dBp
NPSR <sub>X</sub>	Negative Power Supply Rejection, Transmit (note 2) $V_{BB} = 5.0 V_{DC} + 100 \text{ mVrms}, f = 0 \text{ kHz}-50 \text{ kHz}$	40			dBp
PPSR <sub>R</sub>	Positive Power Supply Rejection, Receive (PCM code equals positive zero, $V_{CC}$ = 5.0 $V_{DC}$ + 100 mVrms) f = 0 Hz-4000Hz	40 40 40			dBp dBc dB
	f = 25 kHz-50 kHz	36			dB
NPSR <sub>R</sub>	Negative Power Supply Rejection, Receive (PCM code equals positive zero, $V_{BB} = -5.0 \ V_{DC} + 100 \ mVrms$ ) $f = 0 \ Hz-4000Hz$ A LAW $\mu$ LAW $f = 4 \ kHz-25 \ kHz$ $f = 25 \ kHz-50 \ kHz$	40 40 40			dBp dBc dB dB
SOS	Spurious out-of-band Signals at the Channel Output 0 dBm0, 300 Hz-3400 Hz input PCM applied at D <sub>R</sub> 4600 Hz-7600 Hz 7600 Hz 8400 Hz 8400 Hz 8400 Hz	36		-32 -40 -32	dB dB dB

## TRANSMISSION CHARACTERISTICS (continued).

## DISTORTION

Symbol	Parameter		Min.	Тур.	Max.	Unit
STDX	Signal to Total Distortion (sinusoidal test method)					
or						
STD <sub>R</sub>	Transmit or Receive Half-channel					dBp
	Level = 3.0 dBm0		33			(ALAW)
	= 0  dBm0 to - 30  dBm0		36			
	= -40  dBm0	XMT	29			dBc
		RCV	30			(µLAW)
	= - 55 dBm0	XMT	14			
		RCV	15			
SFD <sub>X</sub>	Single Frequency Distortion, Transmit (T <sub>A</sub> = 25°C)				- 46	dB
SFD <sub>R</sub>	Single Frequency Distortion, Receive (T <sub>A</sub> = 25°C)				- 46	dB
IMD	Intermodulation Distortion				- 41	dB
	Loop Around Measurement, $VF_XI^+ = -4$ dBm0 to					
	- 21 dBm0, two Frequencies in the Range 300 Hz-3400 Hz					

#### **CROSSTALK**

Symbol	Parameter	Min.	Тур.	Max.	Unit
CT <sub>X-R</sub>	Transmit to Receive Crosstalk, 0dBm0 Transmit f = 300 Hz-3400 Hz, D <sub>R</sub> = Steady PCM Code ETC5064/67 ETC5064-X/67-X		- 90	- 75 - 65	dB dB
CT <sub>R-X</sub>	Receive to Transmit Crosstalk, 0dBm0 Receive Level (note 2) f = 300 Hz-3400 Hz, VF <sub>X</sub> I = 0 V ETC5064/67 ETC5064-X/67-X		- 90	- 70 - 65	dB dB

#### **POWER AMPLIFIERS**

Symbol	Parameter	Min.	Тур.	Max.	Unit
$V_{OL}$	Maximum 0 dBm0 Level for Better than $\pm$ 0.1 dB Linearity Over the Range 10 dBm0 to + 3 dBm0 (balanced load, $R_L$ connected between VPO $^+$ and VPO $^-$ )				Vrms
	$R_{L} = 600 \Omega$ $R_{L} = 1200 \Omega$ $R_{I} = 30 \text{ k}\Omega$	33 3.5 4.0			
S/D <sub>P</sub>	Signal/Distortion $R_L = 600 \Omega$ , 0 dBm0	50			dB

Notes: 1. Measured by extrapolation from the distortion test results.
2. PPSRX, NPSRX, CTR-X measured with a -50dBm0 activating signal applied at VF<sub>X</sub>I<sup>+</sup>

## ENCODING FORMAT AT DX OUTPUT

	A-Law (Including even bit inversion)	μ <b>Law</b>
V <sub>IN</sub> (at GS <sub>X</sub> ) = + Full-scale	1 0 1 0 1 0 1 0	1 0 0 0 0 0 0
$V_{IN}$ (at $GS_X$ ) = 0 V	1 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1	1 1 1 1 1 1 1 1 0 1 1 1 1 1 1 1 1 1 1 1
V <sub>IN</sub> (at GS <sub>X</sub> ) = - Full-scale	0 0 1 0 1 0 1 0	0 0 0 0 0 0 0



#### **APPLICATION INFORMATION**

#### **POWER SUPPLIES**

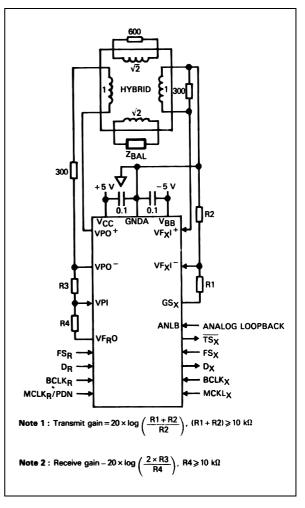
While the pins at the ETC506X family are well protected against electrical misure, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should be used.

All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This minimizes the interaction of ground return currents flowing through a common bus impedance.  $0.1\mu F$  supply decoupling capacitors should be connected from this common ground point to VCC and VBB as close to the device as possible.

For best performance, the ground point of each CODEC/FILTER on a card should be connected to a common card ground in star formation, rather than via a ground bus. This common ground point should be decoupled to VCC and VBB with  $10\mu F$  capacitors

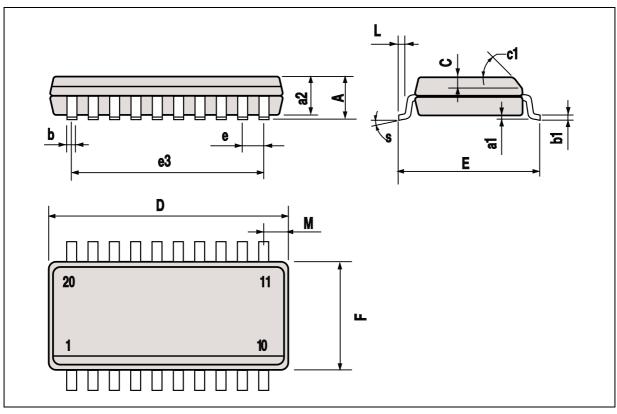
For best performance,  $\overline{TSx}$  should be grounded if not used.

Figure 4: Typical Asynchronous Application.



## **SO20 PACKAGE MECHANICAL DATA**

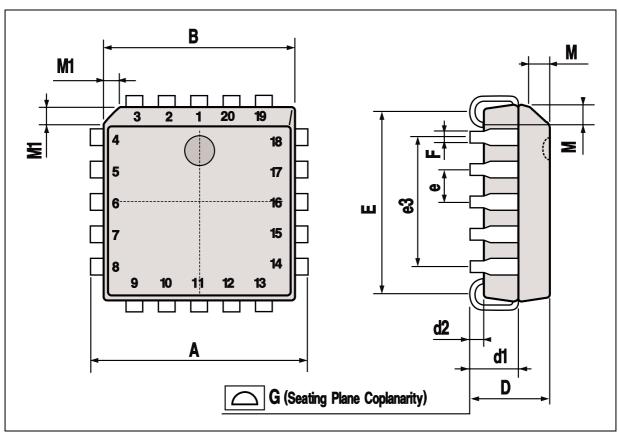
DIM.	mm			inch			
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А			2.65			0.104	
a1	0.1		0.2	0.004		0.008	
a2			2.45			0.096	
b	0.35		0.49	0.014		0.019	
b1	0.23		0.32	0.009		0.013	
С		0.5			0.020		
c1			45°	(typ.)			
D	12.6		13.0	0.496		0.510	
E	10		10.65	0.394		0.419	
е		1.27			0.050		
e3		11.43			0.450		
F	7.4		7.6	0.291		0.300	
L	0.5		1.27	0.020		0.050	
М			0.75			0.030	
S	8° (max.)						



## ETC5064 - ETC5064-X - ETC5067 - ETC5067-X

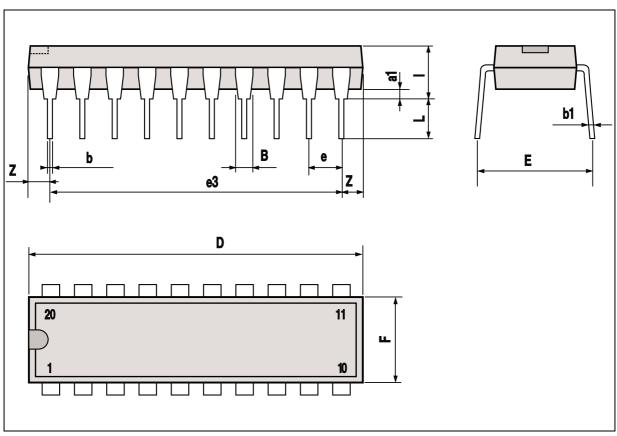
## PLCC20 PACKAGE MECHANICAL DATA

DIM.	mm			inch			
<b>2</b>	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α	9.78		10.03	0.385		0.395	
В	8.89		9.04	0.350		0.356	
D	4.2		4.57	0.165		0.180	
d1		2.54			0.100		
d2		0.56			0.022		
E	7.37		8.38	0.290		0.330	
е		1.27			0.050		
e3		5.08			0.200		
F		0.38			0.015		
G			0.101			0.004	
М		1.27			0.050		
M1		1.14			0.045		



## **DIP20 PACKAGE MECHANICAL DATA**

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
a1	0.254			0.010			
В	1.39		1.65	0.055		0.065	
b		0.45			0.018		
b1		0.25			0.010		
D			25.4			1.000	
E		8.5			0.335		
е		2.54			0.100		
e3		22.86			0.900		
F			7.1			0.280	
I			3.93			0.155	
L		3.3			0.130		
Z			1.34			0.053	



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